

Title (en)

COPPER ALLOY PLATE STRIP FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, COMPONENT, TERMINAL, BUSBAR AND MOVABLE PIECE FOR RELAYS

Title (de)

KUPFERLEGIERUNGSBAND FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNGEN, KOMPONENTE, ANSCHLUSSKLEMME, SAMMELSCHIENE UND BEWEGLICHES TEIL FÜR RELAIS

Title (fr)

BANDE DE TÔLE EN ALLIAGE DE CUIVRE POUR MATÉRIEL ÉLECTRONIQUE ET ÉLECTRIQUE, COMPOSANT, BORNE, BARRE OMNIBUS ET PIÈCE MOBILE POUR DES RELAIS

Publication

EP 3438299 B1 20230503 (EN)

Application

EP 17775267 A 20170329

Priority

- JP 2016069079 A 20160330
- JP 2017063258 A 20170328
- JP 2017012993 W 20170329

Abstract (en)

[origin: EP3438299A1] A copper alloy for electronic and electrical equipment is provided, including: 0.15 mass% or greater and less than 0.35 mass % of Mg; 0.0005 mass% or greater and less than 0.01 mass% of P; and a remainder which is formed of Cu and unavoidable impurities, in which a conductivity is greater than 75% IACS, a content [Mg] (mass%) of Mg and a content [P] (mass%) of P satisfy a relational expression of $[Mg] + 20 \times [P] < 0.5$, and a content of H is 10 mass ppm or less, a content of O is 100 mass ppm or less, a content of S is 50 mass ppm or less, and a content of C is 10 mass ppm or less.

IPC 8 full level

C22C 9/00 (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP KR US)

C21D 9/46 (2013.01 - US); **C22C 9/00** (2013.01 - EP KR US); **C22F 1/08** (2013.01 - EP KR); **H01B 1/02** (2013.01 - KR); **H01B 1/026** (2013.01 - EP); **H01B 5/02** (2013.01 - KR); **H01H 50/14** (2013.01 - KR); **H01H 50/56** (2013.01 - KR); **H01R 4/58** (2013.01 - KR); **H01R 13/03** (2013.01 - KR US); **H01B 1/02** (2013.01 - US); **H01B 5/02** (2013.01 - US)

Cited by

EP4067518A4; EP4067517A4; EP4074848A4; US11203806B2; US11655523B2; US10676803B2; US11104977B2; US11319615B2; US11920228B2

Designated contracting state (EPC)

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EP 3438299 A1 20190206; **EP 3438299 A4 20191218**; **EP 3438299 B1 20230503**; CN 108431256 A 20180821; JP 2017186662 A 20171012; JP 6226097 B2 20171108; KR 102327539 B1 20211116; KR 20180125446 A 20181123; MX 2018011711 A 20181219; TW 201807204 A 20180301; TW I709651 B 20201111

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